

COVER FILM AND ELECTRONIC COMPONENT PACKAGE

ABSTRACT

Disclosed are: a cover film having arrange, in the following order, a substrate layer, an intermediate layer, a peel layer, and a heat seal layer, wherein the peel layer contains a resin composition essentially consisting of 50 to 80 mass% of one or more copolymers selected from styrene-diene block copolymers and styrene-diene graft copolymers, and 50 to 20 mass% of an ethylene-a-olefin copolymer, and has a Vicat softening temperature of 55 to 80 °C, and the heat seal layer contains a styrene-(meth)acrylate copolymer having a styrene content of 50 to 80 mass%, and an electronic component package using the cover film as a carrier tape lid.

Figure.1